Introduction to Zynq Hardware Lab 2 PS Configuration Part 1 & Hello World



November 2013 Version 03



Lab 2 Overview

At the conclusion of Lab 1, an ARM Processing System was added to the IP Integrator block design. The Zynq Re-customize IP tool appeared when we double-clicked the IP in the block design. In this lab, we will configure our processing subsystem by adding a UART peripheral, configuring internal clocking resources and setting up our DDR memory controller. When done, we'll export our design to the Software Development Kit (SDK) and create a simple Hello World application.

Lab 2 Objectives

When you have completed Lab 2, you will know how to do the following:

- Enable and map a Zyng PS UART peripheral
- Configure Memory and Clocks for the Zyng PS
- Build the hardware platform
- Export a design to SDK
- Create and run a Hello World application

Experiment 1: Enable and map a Zyng PS UART peripheral

To start, we'll do something very simple by enabling a single UART peripheral in the design and map it to the Multiplexed I/O (MIO).

Experiment 1 General Instruction:

Set the Bank voltages to LVCMOS 3.3V for Bank 0 and LVCMOS 1.8V for Bank 1. Enable the UART1 peripheral and map it to MIO[48:49].

Experiment 1 Step-by-Step Instructions:

1. If not already open, open the ZynqDesign project and open the Block Design, **Z_system.bd**. Double-click the Zynq Processing System to customize the IP.



The Zynq Block Design window shows that no ARM peripherals or Flash Memory interface are currently enabled. You can determine this since all I/O Peripheral and Flash Memory boxes are unchecked, as shown in the figure below. This also means that no MIOs are connected.

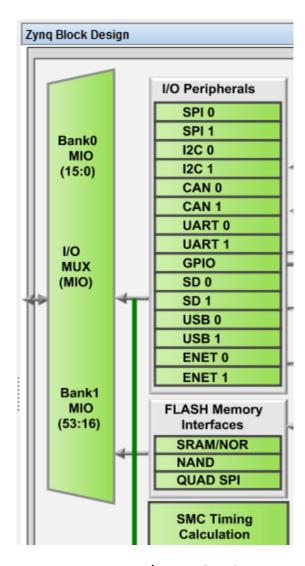


Figure 1 - Zynq I/O Peripherals



2. Click anywhere in the I/O Peripherals Box or select **MIO Configuration** from the Page Navigator. This will open the MIO Configuration page.

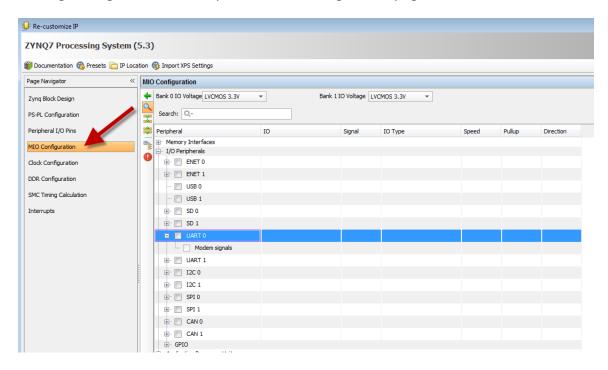


Figure 2 - MIO Configuration

 At the top of the MIO Configuration window, the Bank Voltage settings are listed. Set Bank 0 I/O Voltage to LVCMOS 3.3V and Bank 1 I/O Voltage to LVCMOS 1.8V.

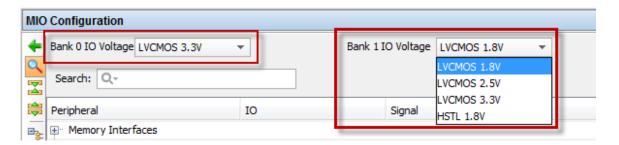


Figure 3 - MIO Bank Voltages

At this time no peripherals are selected. Note, the peripherals are <u>not</u> listed in alphabetical order. The peripherals are listed from top to bottom in order of priority based on their importance in the system (like the Flash) or how limited they are in the possible MIO mappings. The peripherals are ordered with the least flexible at the top and most flexible at the bottom. With the exception of the USB, as it can only be connected in one location.



When mapping out a board, a designer should start at the top of the list and work their way down. A developer has to carefully balance which peripherals will map to the MIO and which ones are mapped to EMIO. However, to simplify this experiment, we will focus just on a single peripheral to show how the process works.

4. There are two UARTs available. Check the box for **UART1**. Click the pull-down for the I/O. Notice that UART1 can be placed on several MIO locations as well as extended MIO (EMIO). Set the I/O to **MIO48** .. **49**, which happens to be the default.

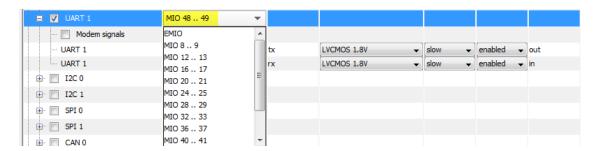


Figure 4 - UART1 Connection

Schematics are included in the support documents folder. If interested, open the schematics to verify the MIO pin connections to the on-board hardware.



5. Select the **Zynq Block Design** link in the Page Navigator. Notice in the I/O Peripherals that UART1 is checked to indicate it is connected.

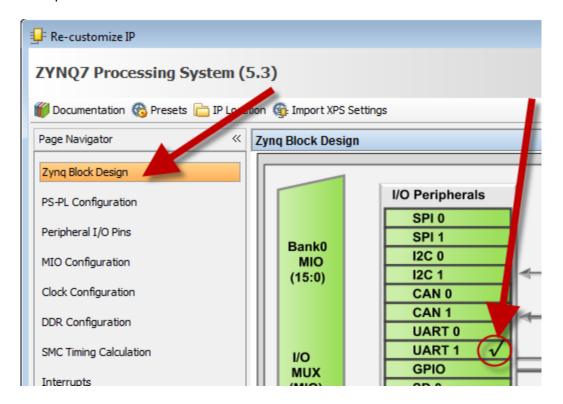


Figure 5 - UART1 MIO Connected

6. In the Zynq Block Design window, click the **General Settings** box or from the Page Navigator window select **PS-PL Configuration**.

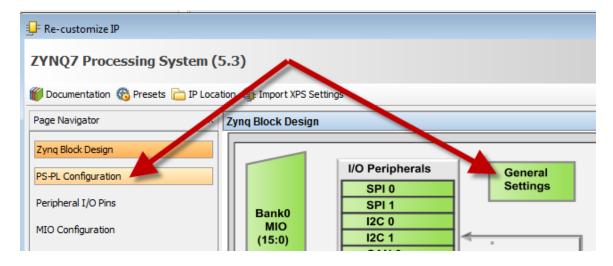


Figure 6 - General Zynq Settings



7. Expand the General section, verify the UART1 Baud Rate is set to 115200.

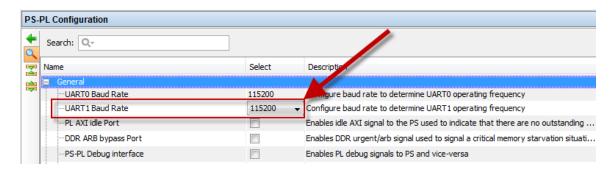


Figure 7 - UART1 Baud Rate Settings

Questions:

Answer the following questions:		
•	What do you think is the purpose of EMIO?	
•	Why are the Peripherals not listed alphabetically in the I/O Peripherals Configuration tool?	
•	Extra Credit: If the Modem Signals are used with one of the UART peripherals, where must they be mapped?	



Experiment 2: Configure Memory and Clocks for the Zynq PS

A few critical Zynq PS elements must be configured before even a simple Hello World can be run. This includes the DDR3 memory, as it is the RAM that will execute the Zynq PS applications. Also, the system clocks must be configured correctly.

Experiment 2 General Instruction:

Configure the Memory GUI for a 32-bit interface using Micron DDR3 memory components. Configure the clocks to operate the CPU at 667 MHz and the memory at 533 MHz.

Experiment 2 Step-by-Step Instructions:

1. Click on the box for **Clock Generation** or select **Clock Configuration** from the Page Navigator.

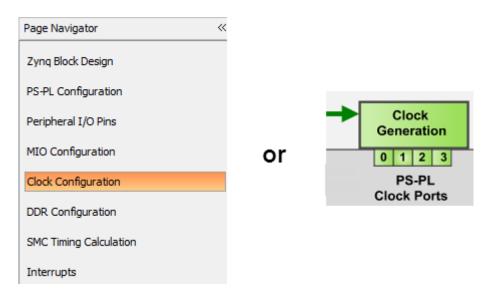


Figure 8 - Clock Configuration



2. Select the **Expand All** button to view all the clocks.

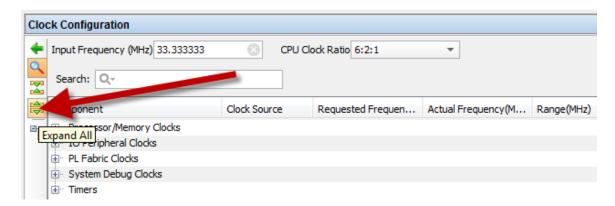


Figure 9 - Expand to see all clocks

- 3. For the most part, the default clock settings match ZedBoard and MicroZed. **Verify** the following:
 - o Input frequency is 33.33333 MHz
 - o CPU frequency is 666.666666 MHz
 - o DDR frequency is 533.333333 MHz

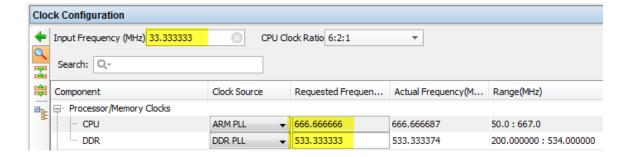


Figure 10 - Clock Settings



4. For now, we will change one of the default settings. One of the PL fabric clocks is enabled but we are not using the PL yet. **Disable** this by unchecking the box for this item.

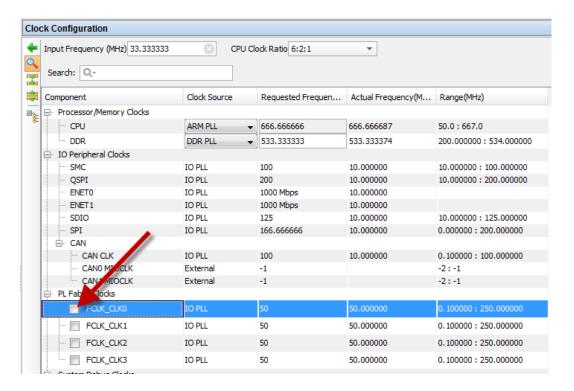


Figure 11 - Disable FCLK CLK0

5. In addition to disabling the default setting for the PL Fabric Clock, we must also disable the default AXI connection to the PL. This is done in *PS-PL Configuration*. Select *PS-PL Configuration* and expand the *GP Master AXI Interface* section, **disable** the *M AXI GPO Interface* by unchecking the box.

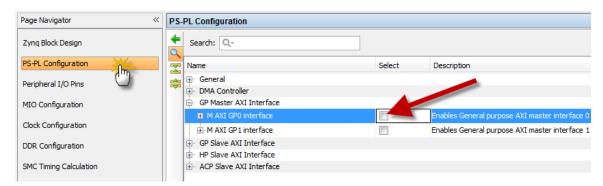


Figure 12 - Disable M AXI GP0 Interface



Next we will configure the memory controller.

6. Select **DDR2/3, LPDDR2 Controller** from the Zynq Block Design or **DDR Configuration** in the Page Navigator.

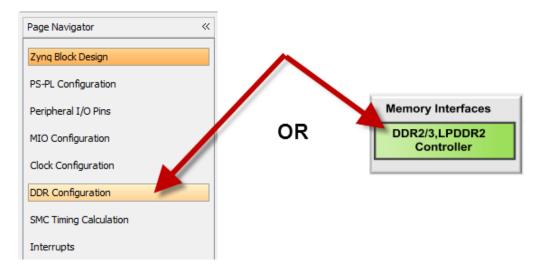


Figure 13 - DDR Memory Configuration

7. Once again, use the **Expand All** button to view all memory parameters. Verify the DDR is **enabled**.

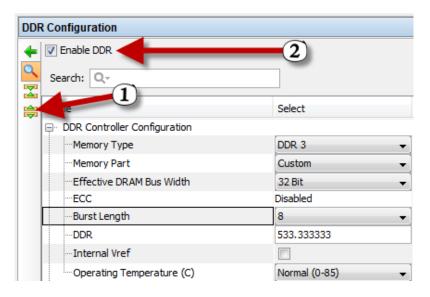


Figure 14 - View Memory Parameters and enable DDR



- 8. We must match the DDR settings to the board we are using. Select the following DDR3 memory parameters for the specific board you are targeting:
 - Memory Type = DDR3
 - Memory Part:
 - o MicroZed = MT41K256M16RE-125
 - o ZedBoard = MT41J128M16HA-15E

Notice how the *Memory Part Configuration* section automatically updates when the *Memory Part* is selected. If your memory device of choice was not in the default catalog, you could select Custom. Then these boxes would be available for manually entering timing parameters for your selected device.

⊢ Memory Part Configuration		
···DRAM IC Bus Width	16 Bits	Width of individual DRAM components.
DRAM Device Capacity	4096 MBits	Storage capacity of individual DRAM components.
Speed Bin	DDR3_1066F	Speed bin of the individual DRAM components.
Bank Address Count (Bits)	3	Number of bank address pins.
Row Address Count (Bits)	15	Number of row address pins.
Col Address Count (Bits)	10	Number of column address bits.
CAS Latency (cycles)	7	Column Access Strobe (CAS) latency in memory clock cycles. It refers to the am
CAS Write Latency (cycles)	6	CAS write latency setting in memory clock cycles.
RAS to CAS Delay (cycles)	7	tRCD. Row address to column address delay time. It is the time required betwe
Precharge Time	7	tRP. Precharge Time is the number of clock cycles needed to terminate access t
tRC (ns)	48.75	Row cycle time (ns)
tRASmin (ns)	35.0	Minimum number of memory clock cycles required between an Active and Precha
tFAW (ns)	40.0	Determines the number of activates that can be performed within a certain wind

Figure 15 – MicroZed Memory Part Configuration

Memory Part Configuration		
····DRAM IC Bus Width	16 Bits	Width of individual DRAM components.
DRAM Device Capacity	2048 MBits	Storage capacity of individual DRAM components.
Speed Bin	DDR3_1066F	Speed bin of the individual DRAM components.
Bank Address Count (Bits)	3	Number of bank address pins.
Row Address Count (Bits)	14	Number of row address pins.
···Col Address Count (Bits)	10	Number of column address bits.
····CAS Latency (cycles)	7	Column Access Strobe (CAS) latency in memory clock cycles. It refers to the am
····CAS Write Latency (cycles)	6	CAS write latency setting in memory clock cycles.
RAS to CAS Delay (cycles)	7	tRCD. Row address to column address delay time. It is the time required betwe
····Precharge Time	7	tRP. Precharge Time is the number of clock cycles needed to terminate access t
····tRC (ns)	49.5	Row cycle time (ns)
tRASmin (ns)	36.0	Minimum number of memory clock cycles required between an Active and Precha
tFAW (ns)	45.0	Determines the number of activates that can be performed within a certain wind

Figure 16 - ZedBoard Memory Part Configuration

9. In the DDR Controller Configuration section, the *Effective DRAM Bus Width* must be assigned to **32-bits** as we are using a 2x16 DDR3 configuration. Since we are using DDR3 on a 7Z010 (or 7Z020) device, the ECC and Burst Length settings are predetermined. Notice also that the operating Frequency has automatically been inherited from the Clock Configuration screen to be 533 MHz.



Lab 2:12

10. Check the box for **Internal Vref**. The operating temperature can remain at the **Normal (0-85) range**.

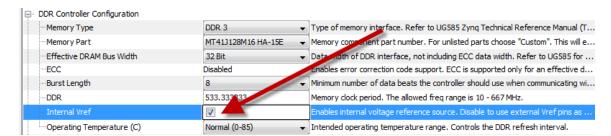


Figure 17 - DDR Controller Configuration (ZedBoard)

Setting the *Training/Board Detail* parameters are next.

11. DRAM Training must be enabled for *Write leveling*, *Read gate*, and *Read data* eye options. **Check those 3 boxes** now. An explanation of what these are is in the Zyng TRM, Section 10.6.8.

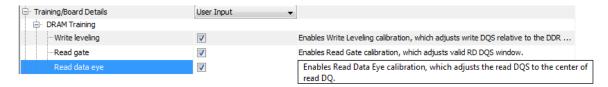


Figure 18 - Training/Board Details

Notice there are four entries to allow for *DQS* to *Clock Delay* (ns) and *Board Delay* (ns) information to be specified for each of the four byte lanes. These numbers assist the training algorithm with a starting point inside the DDR3 data valid window. All delays by default start at 0.0. Keep in mind the parameters for these fields are specific to each individual PCB design <u>and</u> Zynq package.

The values are based on the PCB trace lengths and the specific Zynq package chosen. Vivado already understands which package has been chosen, but the user must enter several values for the PCB trace lengths.

The procedure to calculate these lengths is included in the attached Appendix. If you have enough time after you finish the lab, complete the exercises there. However, in the interest of time, the Delay numbers will be given to you now.



12. Edit the **DQS to Clock Delay** and **Board Delay** settings as show here.

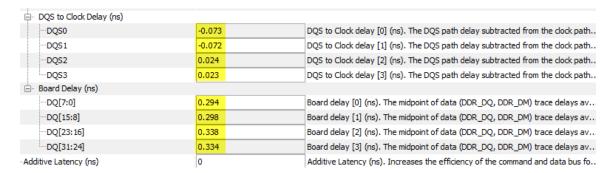


Figure 19 - MicroZed Board Training details

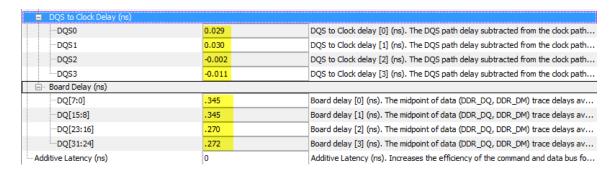


Figure 20 - ZedBoard Board Training details

- 13. Click **OK** to finish configuration of the Zynq PS.
- 14. Save the Block Design.

Questions:

Answer the following questions: Where can the DDR interface speed be set? Where did Vivado get the Memory Part Configuration Settings? Where would you get them for a custom part? What is the maximum speed the DDR3 interface can run at? Extra Credit: What is the slowest?



Experiment 3: Build the hardware platform and export to SDK

A basic ARM hardware platform is now configured. The configuration includes clock and DDR controller settings. It also enables and maps a UART peripheral. Now we'll build the hardware platform and export to the Software Development Kit (SDK) so that an application can be developed.

Experiment 3 General Instruction:

Add a top-level module for the design. Export the hardware to SDK.

Experiment 3 Step-by-Step Instructions:

1. To validate our Zyng block design, click the **Validate Design** button.

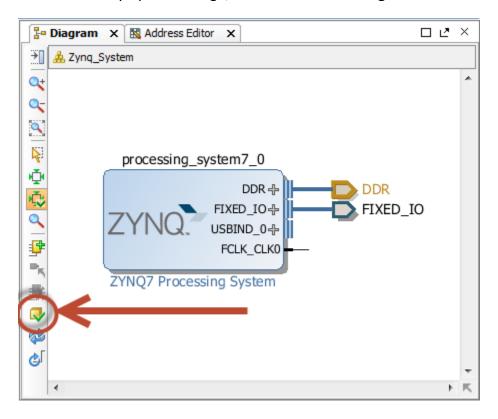


Figure 21 - Validate Block Design



2. If validation is successful, verify the Sources Tab is selected in the Vivado window, right-click on the **Z_system.bd**, then select **Create HDL Wrapper**.

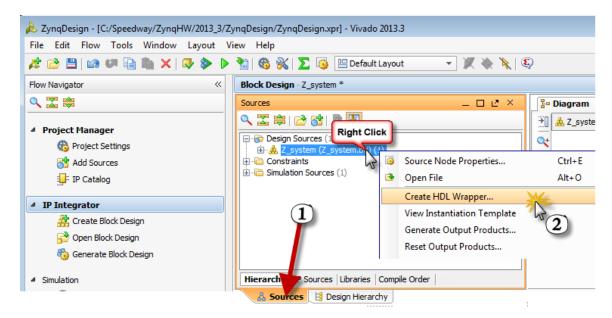


Figure 22 - Create HDL Wrapper

3. Vivado can manage your top-level HDL wrapper for you. Alternatively if this block design is a subset of a larger project, an editable wrapper will be created for instantiation into that project. For this tutorial, we will let Vivado manage our wrapper. Select **OK**.

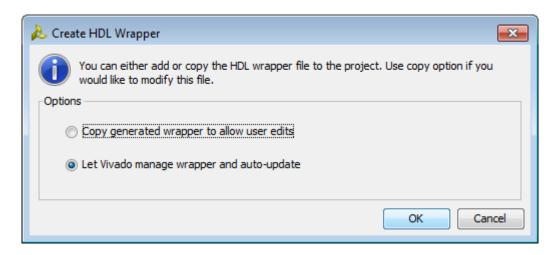


Figure 23 - Create HDL Wrapper options



4. When completed, expand *Design Sources* and double-click on the newly created top-level wrapper, **Z_system_wrapper.v.** You'll see the Z_system instantiation.

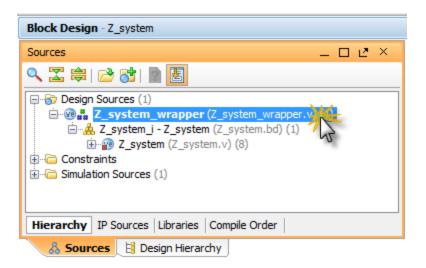


Figure 24 - Design Sources

5. Our design is now ready to be built. Click **Generate Bitstream** from the *Flow Navigator* pane. Note: This is not required as we are not utilizing the PL. However most designs will, thus its good practice to do this.

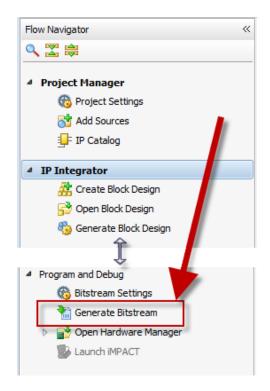


Figure 25 – Generate Bitstream



6. Vivado will warn that no synthesis or implementation results exist and ask to launch these steps. Click **Yes**.

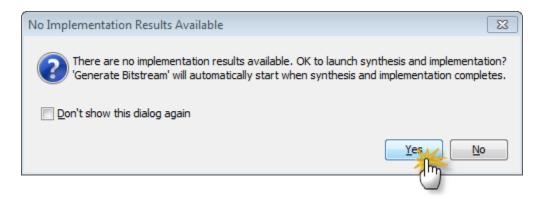


Figure 26 - Launch Synthesis and Implementation

7. This will take a few minutes depending on your PC. When Bitstream Generation has completed, select **Open Implemented Design**. Click **OK**. Opening the implemented design enables Vivado to export the bitstream to SDK.

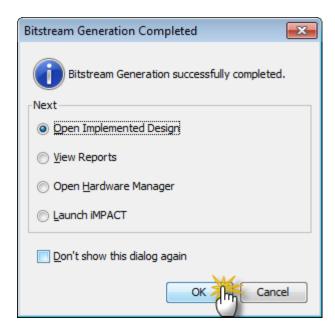


Figure 27 - Open Implemented Design



8. From the pull-down menus at the top of Vivado, select File → Export → Export Hardware for SDK...

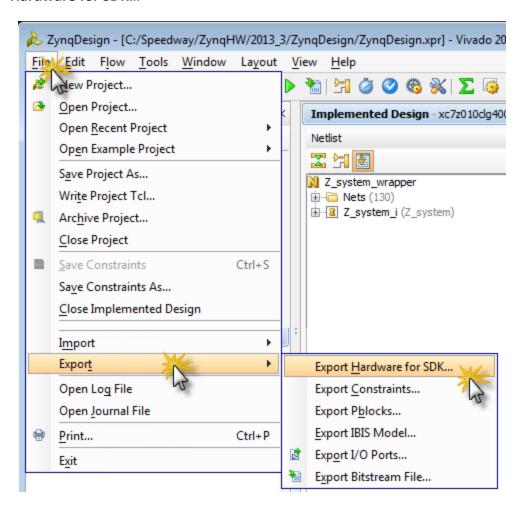


Figure 28 - Export Hardware for SDK...



9. In the next window, notice the Include bitstream box is checked. This was done because we opened an implemented design in our last step. Set the *Export to* and *Workspace* fields to: C:\Speedway\ZynqHW\2013_3\SDK_Workspace

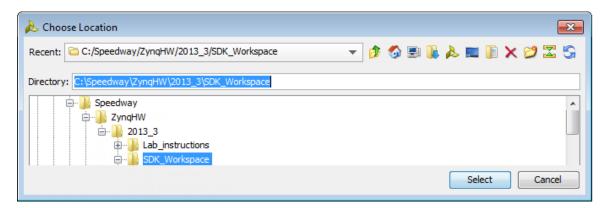


Figure 29 - Export Directory

10. Check the box to Launch SDK. Click OK.

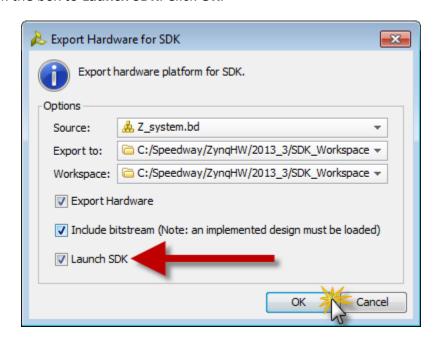


Figure 30 - Export Options



11. Using a file explorer, open the SDK_Workspace directory to see what files were exported. Expand the *hw platform 0* folder:



Figure 31 - Exported Files for SDK

The Vivado design tool exported the Hardware Platform Specification for your design (system.xml in this example) to SDK. In addition to system.xml, there are six more files exported to SDK. They are ps7_init.c, ps7_init.h, ps7_init.tcl, ps7_init.html, ps7_summary.html and Z_system_wrapper.bit.

The system.xml file opens by default when SDK launches. The address map of your system read from this file is shown by default in the SDK window.

The ps7_init.c and ps7_init.h files contain the initialization code for the Zynq Processing System and initialization settings for DDR, clocks, PLLs, and MIOs. SDK uses these settings when initializing the processing system so that applications can be run on top of the processing system. The ps7_init.html displays these settings in an easy to read webpage format.

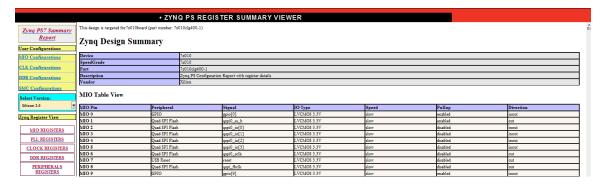


Figure 32 - ps7 init.html (MicroZed)

One more file is created, Z_system_wrapper.bit. This file is the PL bitstream generated when we implemented our design. Currently there is nothing in the PL however a blank bitstream is created that will initialize the PL.



Experiment 4: Create and Run a Hello World application

In this experiment, you will use SDK to create and run a simple Hello World application.

Experiment 4 General Instruction:

Create the Standalone BSP. Generate and run the Hello World application.

Experiment 4 Step-by-Step Instructions:

- 1. Select File → New → Board Support Package.
- 2. Accept the default settings for the standalone BSP OS. Click Finish.

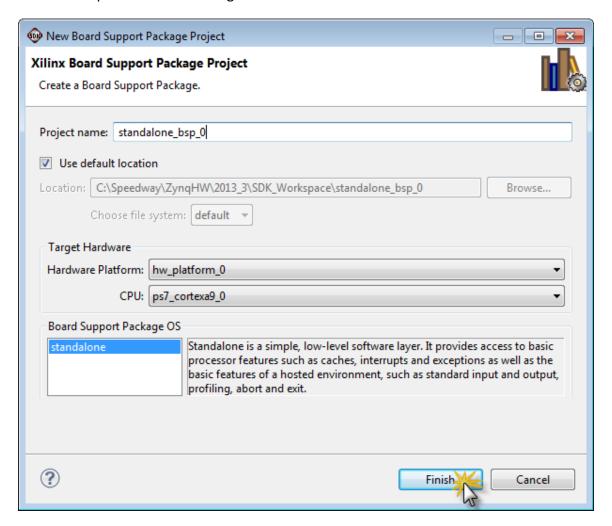


Figure 33 - Standalone BSP



3. Click **standalone**. Note that the **stdin** and **stdout** are automatically set to the ps7 uart 1 peripheral, which is correct.



Figure 34 – stdin and stdout settings

4. Click **Overview**. No changes will be made to the BSP settings. None of the Supported Libraries are needed for this experiment. Click **OK** to accept the defaults and close this dialog. Note: It may take a minute to build the BSP.

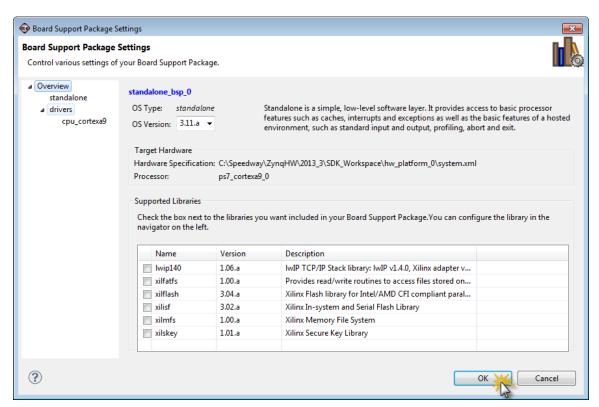


Figure 35 – BSP Settings



Based on the default settings in SDK, the BSP will automatically be built once added to the project. This may take a minute to compile the new BSP. The standalone_bsp_0 is now visible in the Project Explorer.

5. Expand **standalone_bsp_0** under the *Project Explorer*.

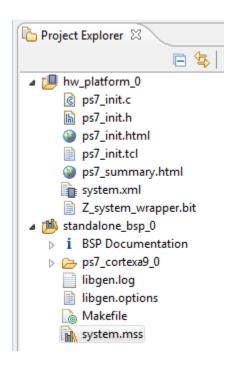


Figure 36 - BSP Added to the Project



- 6. In SDK, select File → New → Application Project.
- 7. Enter the *Project Name* of **Hello_World** and select *Use existing* BSP, **standalone_bsp_0**. Click **Next** >.

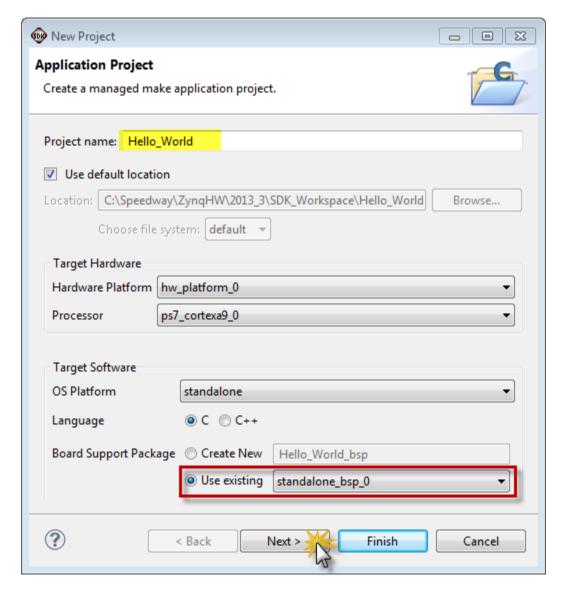


Figure 37 - Application Project Settings



8. Select **Hello World** from the *Available Templates* field. Click **Finish**.

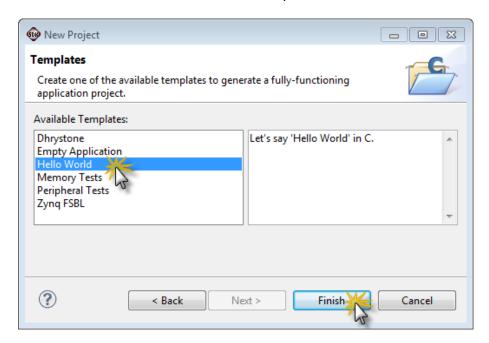


Figure 38 - New Application: Hello World

Hello World will automatically build:

```
00:29:15 **** Build of configuration Debug for project Hello World ****
make all
'Building file: ../src/helloworld.c'
'Invoking: ARM gcc compiler'
arm-xilinx-eabi-gcc -Wall -00 -g3 -c -fmessage-length=0 -I../../standalone_bsp_0/ps7_cortexa9_0/include -MMD -MP
-MF"src/helloworld.d" -MT"src/helloworld.d" -o "src/helloworld.o" "../src/helloworld.c"
'Finished building: ../src/helloworld.c'
'Building file: ../src/platform.c'
'Invoking: ARM gcc compiler'
arm-xilinx-eabi-gcc -Wall -00 -g3 -c -fmessage-length=0 -I../../standalone_bsp_0/ps7_cortexa9_0/include -MMD -MP -MF"src/platform.d" -MT"src/platform.d" -o "src/platform.o" "../src/platform.c"
'Finished building: ../src/platform.c'
'Building target: Hello_World.elf'
'Invoking: ARM gcc linker'
arm-xilinx-eabi-gcc -Wl,-T -Wl,../src/lscript.ld -L../../standalone_bsp_0/ps7_cortexa9_0/lib -o
"Hello_World.elf" ./src/helloworld.o ./src/platform.o -Wl,--start-group,-lxil,-lgcc,-lc,--end-group
'Finished building target: Hello_World.elf'
'Invoking: ARM Print Size'
arm-xilinx-eabi-size Hello_World.elf |tee "Hello_World.elf.size"
                                      hex filename
d1f4 Hello_World.elf
   text
           data
                      bss
                                dec
           1096 29780 53748
  22872
'Finished building: Hello_World.elf.size'
00:29:17 Build Finished (took 2s.936ms)
```

Figure 39 - Hello World Application Automatically Built



Notice that the Hello_World application is now visible in Project Explorer. By default, SDK will build the application automatically after it is added.

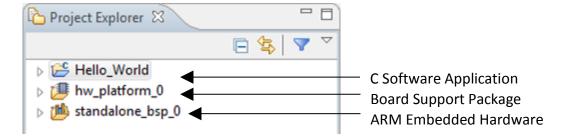


Figure 40 – Project Explorer View with Hello World C Application Added

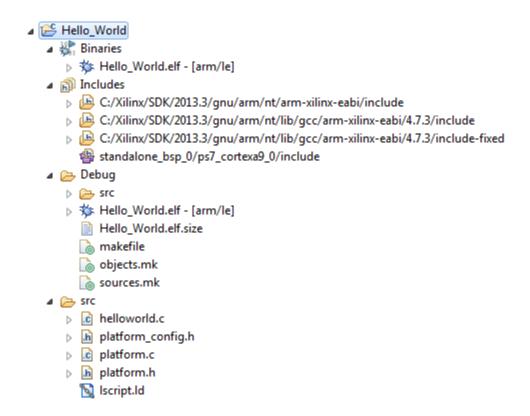


Figure 41 – Hello_World Application Expanded

9. MicroZed users, **Connect a USB cable** between a PC and the microUSB port on MicroZed. **Connect a Xilinx JTAG Programming cable** to J3.

ZedBoard users, **Connect the power cable** to the ZedBoard. **Connect two micro-USB cables** between the Windows Host machine and the ZedBoard connectors J17 (JTAG) and J14 (UART).



10. Set jumpers to Cascaded JTAG Mode:





ZedBoard

MicroZed

Figure 42 – Mode Pin Jumpers

- 11. **ZedBoard Only: Power** on the board. If this is the first time you've connected either of these boards to this computer, you may see Windows install device drivers for the USB-UART and Digilent JTAG.
- 12. Use Device Manager to determine the COM port for the USB-UART. In Windows 7, click **Start** → **Control Panel**, and then click **Device Manager**. Click **Yes** to confirm.
- 13. Expand *Ports*. Note the COM port number for the Cypress Serial device. This example shows COM6.

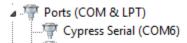


Figure 43 – Find the COM port number for the Serial device

14. Right-click on the **Hello_World** application and select **Run As** → **Run Configurations...**



15. Select Xilinx C/C++ Application (GDB) and then click the 'New' icon .

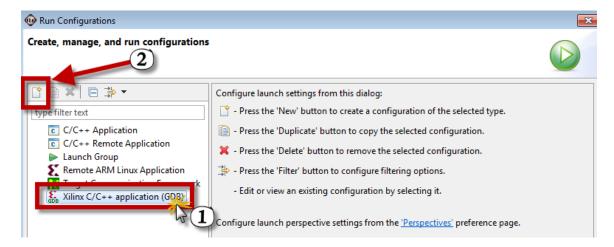


Figure 44 - Create a New Xilinx C/C++ ELF Run Configuration

SDK creates the new Run Configuration and automatically assigns a name to the configuration *capplication name* bebug, which in this case is *Hello World Debug*.

16. Browse through the tabs here to see what's available for this configuration.

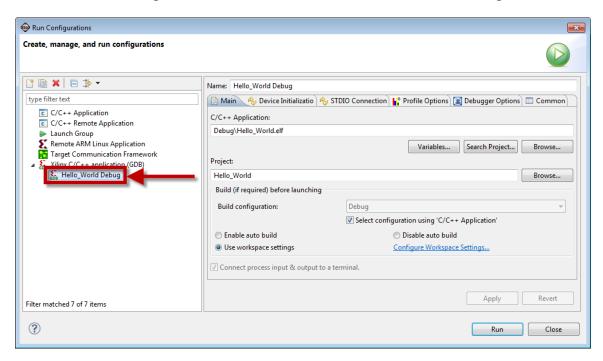


Figure 45 – New Run Configuration

17. Switch to the STDIO Connection tab.



- 18. Check the box for Connect STDIO to Console.
- 19. Select the **PORT** for the USB-UART.
- 20. Set the BAUD Rate to 115200.



Figure 46 - STDIO Connection

21. Click **Apply** and then **Run**.

The tools will now initialize the processor, download the Hello_World.elf to DDR, and then run hello_world. This takes approximately 15 seconds to complete, depending on the USB traffic in your system. You can follow the progress in the lower right corner of SDK.

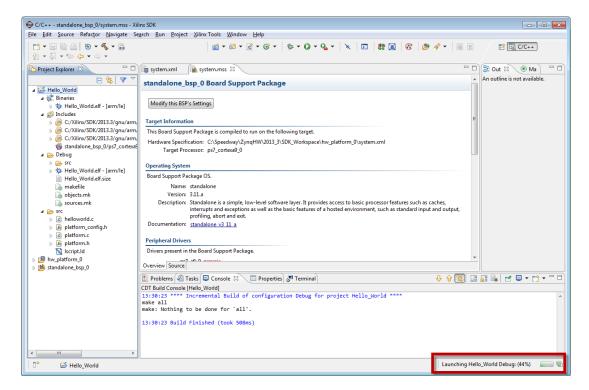


Figure 47 – Launching hello_world Progress



SDK will download the Hello World ELF to the DDR3 and the ARM begins executing the code.

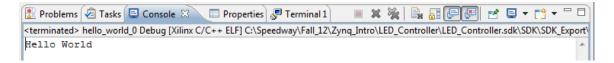


Figure 48 – Hello World Complete

22. Close SDK.

Questions:

Answer the following questions:		
•	Does the Hello World C source include Zynq initialization?	
•	How did the Zynq get initialized in this Hello World experiment?	



Exploring Further

If you have more time and would like to investigate more...

• Read the Appendix on calculating DDR 3 PCB Delays

This concludes Lab 2.

Revision History

Date	Version	Revision
6 Nov 13	02	Initial Draft
19 Nov 13	03	Pilot updates

Resources

www.microzed.org

www.zedboard.org

www.xilinx.com/zynq

www.xilinx.com/sdk

www.xilinx.com/vivado



Appendix – Calculating DDR 3 PCB Lengths (ZedBoard)

Zynq allows for up to 4 memory devices to be configured for DDR3 4x8 fly-by topology. ZedBoard is configured for DDR3 2x16 fly-by topology. For a description of fly-by topology, see Micron TN-41-13. Figures 1 and Figure 7 show the basic daisy-chain topology used for Command/Address/Control/Clocks.

With the two DDR3 chips, the DQS's and DQ's are all point-to-point. Those values can easily be obtained from a simple trace length report. However, because of the fly-by routing, the CLK routing is daisy-chained. ZedBoard only has one DDR3 clock pair, which goes to IC26 first and then IC25. The CLK trace length in the report is going to be the total length. Getting the CLK2 and CLK3 lengths will be more challenging, and we'll have to open the layout to get this measurement.

First, let's calculate the length values that we can easily get from a trace length report.

1. A trace length report for ZedBoard is provided in the **Support_documents** folder. Open <u>ZedBoard RevB PCB Trace Length Report.txt</u> now.

All the DDR3 signals are prefixed in this report with "DDR3-" so these are easy to search. For differential pairs, calculate the average length of the P and N traces. For the data busses, calculate the average of the Minimum and Maximum values in the set. Each chip services two byte groups, so you'll find 16 DQ's and 2 DQS's per chip, but only one CLK. Therefore, the CLK lengths for byte groups 0 and 1 are the same; CLK2 and CLK3 are also the same.

2. Use the trace length report to calculate and then enter the trace lengths for CLKO, DQSO, and DQ[7:0].

Pin Group	ZedBoard Traces Used in Calculation	Length (mm)
CLKO	DDR3-CLK0_N,	
CLNU	DDR3-CLK0_P	
DQS0	DDR3-DQS0_N,	
DQSU	DDR3-DQS0_P	
DQ[7:0]	DDR3-D[7:0]	

Since CLK2 and CLK3 must be calculated differently, we'll look at them next. CLK2 is associated with Byte Group 2. CLK3 is associated with Byte Group 3. Byte Groups 2 and 3 are driven from IC26. Since traces DDR3-CLK0_P/N route daisy-chain first to IC26 and then IC25, the length to the trace segments between Zynq and IC26 must be measured manually. This must be done in Altium or Altium Viewer, which is the layout source for



ZedBoard. To simplify this exercise, these trace segments were previously measured and screen captured.

3. Average these two trace segments and enter for CLK2 and CLK3.

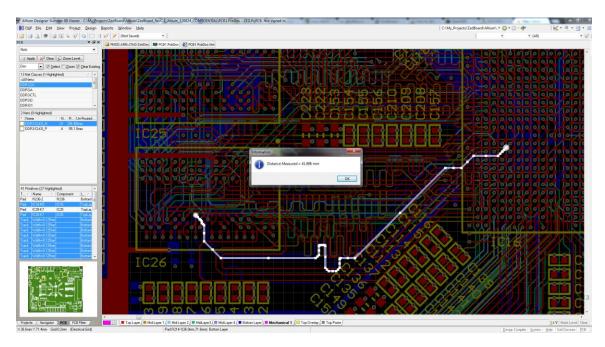


Figure 49 - Trace Segment DDR3-CLK0_N = 41.998 mm

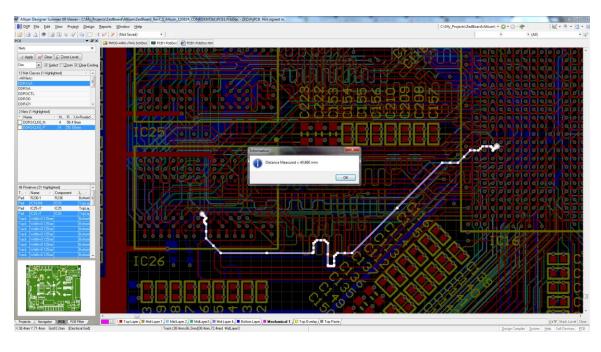


Figure 50 - Trace Segment DDR3-CLK0_P = 40.860 mm



4. Calculate the remaining lengths in similar fashion. Enter these now.

Pin Group	Length (mm)
CLK1	
DQS1	
DQS2	
DQS3	
DQ[15:8]	
DQ[23:16]	
DQ[31:24]	

The completed worksheet should appear as shown below.

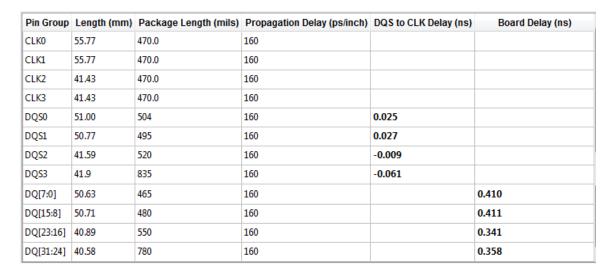


Figure 51 – ZedBoard PCB Lengths Calculated and Entered



Questions:

Answer the following questions:			
In a multi-component memory design, how do you calculate the CLK trace length for the first component in the daisy chain?			
How do you calculate the trace length for a DQ byte group?			



Answers

Experiment 1

What do you think is the purpose of EMIO?

MIO pins are dedicated I/O in the Processing Subsystem. EMIO provide PL fabric access to PS peripherals, which can then be connected to PL I/O.

• Why are the Peripherals not listed alphabetically in the I/O Peripherals Configuration tool?

The peripherals are listed in order of priority. Peripherals on the top of the list generally need to be connected first and less MIO options.

• Extra Credit: If the Modem Signals are used with one of the UART peripherals, where must they be mapped?

EMIO

Experiment 2

• Where can the DDR interface speed be set?

In the Clock Configuration window or the DDR Configuration window.

• Where did Vivado get the Memory Part Configuration Settings? Where would you get them for a custom part?

Vivado has a preset library of memory part details. With each release of Vivado, Xilinx adds new memory devices to this library. If you use a custom part, these values must be extracted from the specific DDR datasheet.

• What is the maximum speed the DDR3 interface can run at? Extra Credit: What is the slowest?

533MHz.

Slowest? It depends on the DDR3 memory device. Even though Vivado lists the slowest speed as 10MHz, the DDR3 memory device's internal PLL may not be able to run that slow. When a known memory device is selected, Vivado prevents users from setting a speed to slow. In this case, 303MHz (Tck max = 3.3ns)



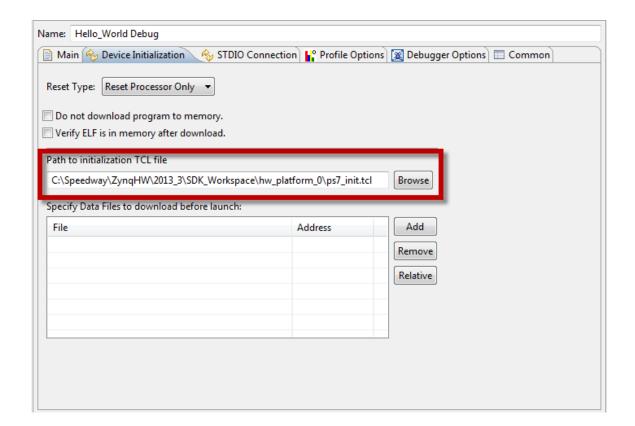
Experiment 4

• Does the Hello World C source include Zyng initialization?

No

How did the Zyng get initialized in this Hello World experiment?

When you created the Run Configuration, there was a Device Initialization tab. Here there is a field to point to an initialization TCL file. This is set by default to the ps7_init.tcl file that was created as part of the Export to SDK. Inside this TCL, you will find a number of XMD commands that initialize all the registers exactly how you specified in Vivado.





Appendix

Pin Group	ZedBoard Traces to Average	Length (mm)
CLK0	DDR3-CLK0_N, DDR3-CLK0_P	Average(56.4267, 55.1225) = 55.7746 mm
DQS0	DDR3-DQS0_N, DDR3-DQS0_P	Average (51.3839,50.6222) = 51.00305 mm
DQ[7:0]	DDR3-D[7:0]	Min = 50.1401 Max = 51.1172 Avg = 50.6287 mm

Pin Group	Length (mm)
CLK1	55.77
DQS1	50.77
DQS2	41.59
DQS3	41.90
DQ[15:8]	50.71
DQ[23:16]	40.89
DQ[31:24]	40.58

• In a multi-component memory design, how do you calculate the CLK trace length for the first component in the daisy chain?

You must open the layout tool to find the trace lengths for clk_p and clk_n from the Zynq to that component. Then average the _p and _n lengths.

• How do you calculate the trace length for a DQ byte group?

Find the minimum length and the maximum length out of the 8 traces then average them.

